

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
51	550	Mold33 near3 apparatus and substrate and (stiffener or dam)	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 16:59
52	51	438/120.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:00
53	565	257/667.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:00
54	5924	257/787.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:00
55	5115	257/678.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:29
56	5107	257/778.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:29
57	19	(257/e23.001).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:30
58	54	(257/e23.18).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:30
59	1495	(257/e23.039).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/04/03 19:30
60	559	Mold33 near3 apparatus and substrate and (stiffener or dam)	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
61	59	438/120.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
62	595	257/667.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
63	5993	257/787.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
64	5249	257/678.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
65	5255	257/778.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
66	10	(257/e23.001).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
67	55	(257/e23.18).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
68	1335	(257/e23.039).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:50
69	52	(*4891687)*5929517*(*5973389)*6020221*(*6279758)*6284569*(*6303985)*6326544*(*6426565)*6407777*6486562*(*6517662)*6519843*6584897*6599365*6724071*.PN.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 16:51
70	2	(*4710419*).PN.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 17:23
71	2	(*5650593*).PN.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 17:25
72	5723	ppray53 near3 mold33	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 17:32
73	560	522 and semiconductor and substrate	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/08/08 17:32
74	565	Mold33 near3 apparatus and substrate and (stiffener or dam)	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
75	59	438/120.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
76	597	257/667.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
77	597	257/667.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
78	4021	257/787.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
79	5330	257/678.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
80	5330	257/678.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
81	5316	257/778.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
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83	59	(257/e23.18).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
84	5589	(257/e23.039).ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
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88	4021	257/787.ccls.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
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96	2	(*5650593*).PN.	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
97	5682	ppray53 near3 mold33	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18
98	575	545 and semiconductor and substrate	US-PGpub; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	CON	2007/10/12 14:18

10/12/07 3:26:08 PM

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